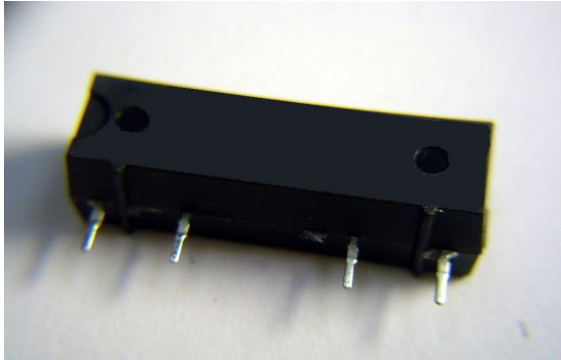




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Features

- * SIL 1 form A - 10 W epoxy molded dry reed relays
- * Diëlectric withstanding voltage of 1000 VDC over open contact
- * Designed for ATE markets where high isolation and breakdown voltages are needed
- * Completely washable
- * High density board mounting
- * Optional internal diode & magnetic shield

Technical data (@ 25 °C)

Input Data / Coil Data	Conditions		unit
Nominal voltage		24	V
Coil resistance	Ohms (± 10%)	2100	ohm
Must operate / Pull in V		18	V
Must release / Drop out V		2	V
Nominal input power		275	mW
Maximum voltage		28	V

Output Data/Contact Data

Contact form		1A	
Max. switching power	Max DC/PeakAC Resistive	10	W
Max. switching voltage	Max DC/PeakAC Resistive	500	V
Max. switching current	Max DC/PeakAC Resistive	0,5	A
Max. carry current	Max DC/PeakAC Resistive	1	A
Switching frequency		500	Hz
Max. contact resistance	50 mV, 10 mA	100	mOhm
Life expectancy	Signal level 1 V, 10 mA	min. 100 x 10 ⁶ operations	



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Technical data (@ 25 °C)

Relay parameters	Conditions	MIN	TYP	MAX	UNITS
Insulation resistance	between all isolated pins at 100 V, 25 °C, 40% RH	10 ¹¹	10 ¹²		Ohms
Capacitance	Across open contacts		-		
	Open contact to coil		-		
Dielectric strength	Between contacts	1000			VDC / peak AC
	Contacts to coil	2500			VDC / peak AC
Operate time (incl.bounce)	At nominal coil voltage, 10 Hz Sq.W.		0.25	0.50	ms
Release time	Zener-diode suppression		0.20	0.30	ms

Environmental Ratings

Operating temperature		-40		85	°C
Storage temperature		-40		125	°C
Shock resistance	1/2 sine wave duration 11 ms			100	g
Vibration resistance	5 to 2000 Hz			20	g
Weight			2		grams
Humidity test	40 °C, 93% RH, 21 days				
Terminal solderability	IEC 68-2-20 test Ta, method 1, solderbath temp 235 °C, immersion time 2 sec				
Resistance to solder heat	IEC 68-2-20 test Tb, method 1A, solderbath temp 260 °C, immersion time 10 sec				

Dimensions & Pin layout

